

Technical Data Sheet

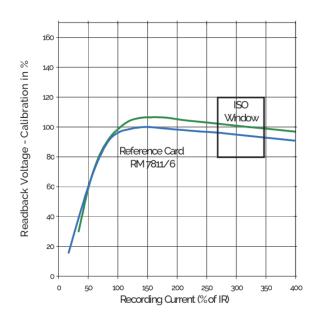
Magnetic Transfer Tapes

Type:

DIHDGL19

HiCo 2750 Oe double gold

Saturation Curve

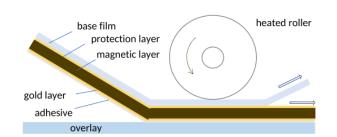


Film - Coating Composite



base film protection layer magnetic layer gold layer adhesive

Transfer Process



General Characteristics	
Base film material	Polyester
Magnetic layer material	Ferrite
Color	Gold (PMS 132)
Thickness Characteristics	
Base film	19 ± 1 μm
Protection layer	7.5 ± 1 μm
Magnetic layer	10 ± 2 μm
Gold back coat layer	9 ± 1 μm
Adhesive	2 ± 0.5 μm
Activation temperature	80° C
Magnetic Characteristics	

Magnetic characteristics	
Coercivity H _c	219 ⁺¹⁶ -8 kA/m (2750 Oe)
Retentivity M _r	≥ 8.000 µm.G
Squareness	≥ 0,8
Switching field SFD	≤ 0,5
Orientation factor	≥ 2,0

Signal Amplitude CharacteristicsSignal amplitude U_{A1} $100 \pm 15 \% U_R$ Signal amplitude U_{i1} ≤ $126 \% U_R$ Signal amplitude U_{A2} ≥ $80 \% U_R$ Signal amplitude U_{i2} ≥ $65 \% U_R$ Resolution U_{A3} ≥ $70 \% U_{A2}$ Erasure U_{A4} ≤ $3 \% U_R$ Extra pulse U_{i4} ≤ $5 \% U_R$

Wear Resistance Characteristics

According to ISO/IEC 7811-6 / 10373-1

Average signal amplitude $U_{A \text{ after}} \ge 60\% \ U_{A \text{ before}}$ Individual signal amplitude $U_{i \text{ after}} \ge 80\% \ U_{A \text{ after}}$

Chemical Resistance Characteristics

According to ISO/IEC 7811-6 / 10373-1

Average signal amplitude $U_{A \text{ after}} \ge 90\% \ U_{A \text{ before}}$ Individual signal amplitude $U_{i \text{ after}} \ge 90\% \ U_{A \text{ after}}$

Storage Conditions

For tape with adhesive:

The allowed storage period for the reel is 2 years from the date of certificate under the following conditions:

Temperature: 10°C - 28°C
Humidity: 20%-60% RH
Additional pressure on the windings shall be avoided

The information given in the technical datasheet is based on our current knowledge. This information merely describes the product's properties but do not guarantee them from a legal point of view. We recommend to conduct tests before industrial use in order to check whether the product is suitable for the expected application.

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